TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130128001
MSA ISO leadframe - CMS C1301064
Information Only

Date: 1/31/2013
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130128001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO7220AQDRQ1	null
ISO7221AQDRQ1	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130128001	**PCN Date:**	01/31/2012
Title:	MSA ISO 1/2 etch leadframe - CMS C1301064		

Customer Contact:	PCN Manager	**Phone:**	+1(214) 480-6037	**Dept:**	Quality Services

Change Type:

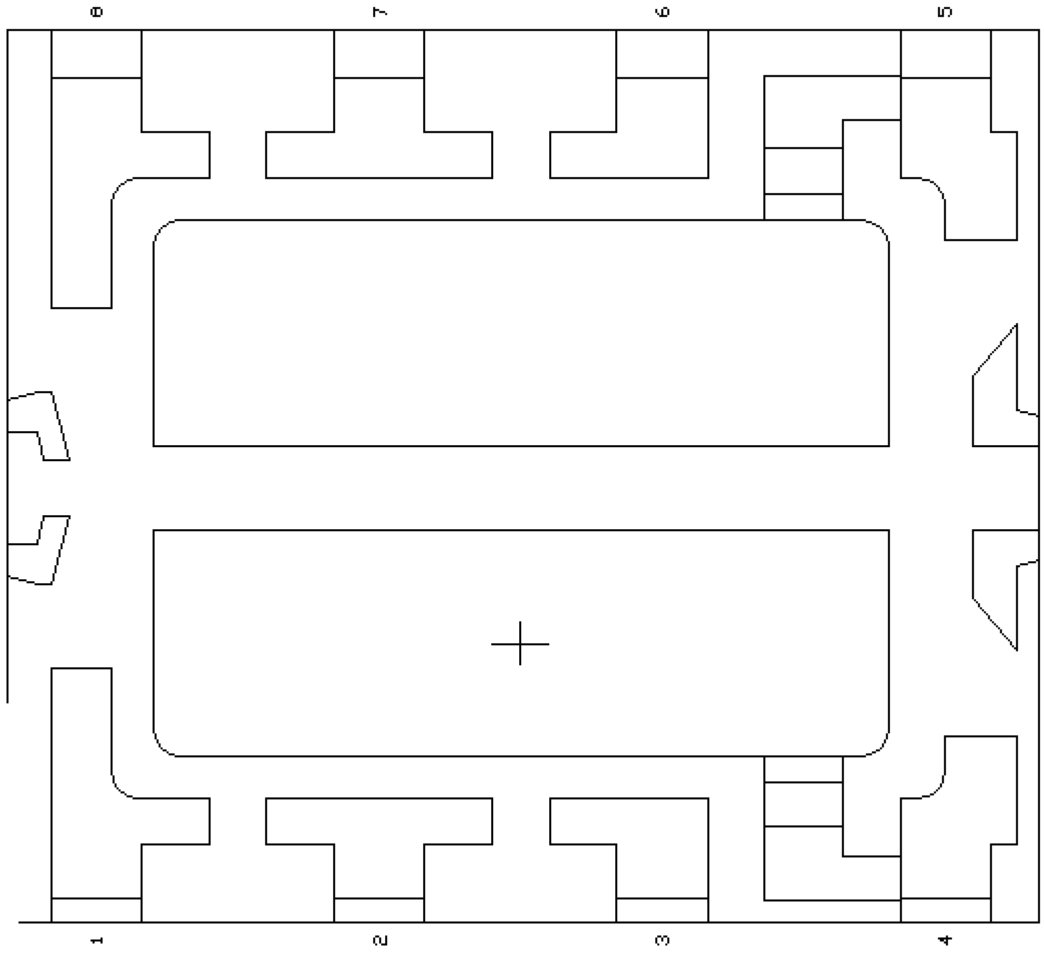
☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

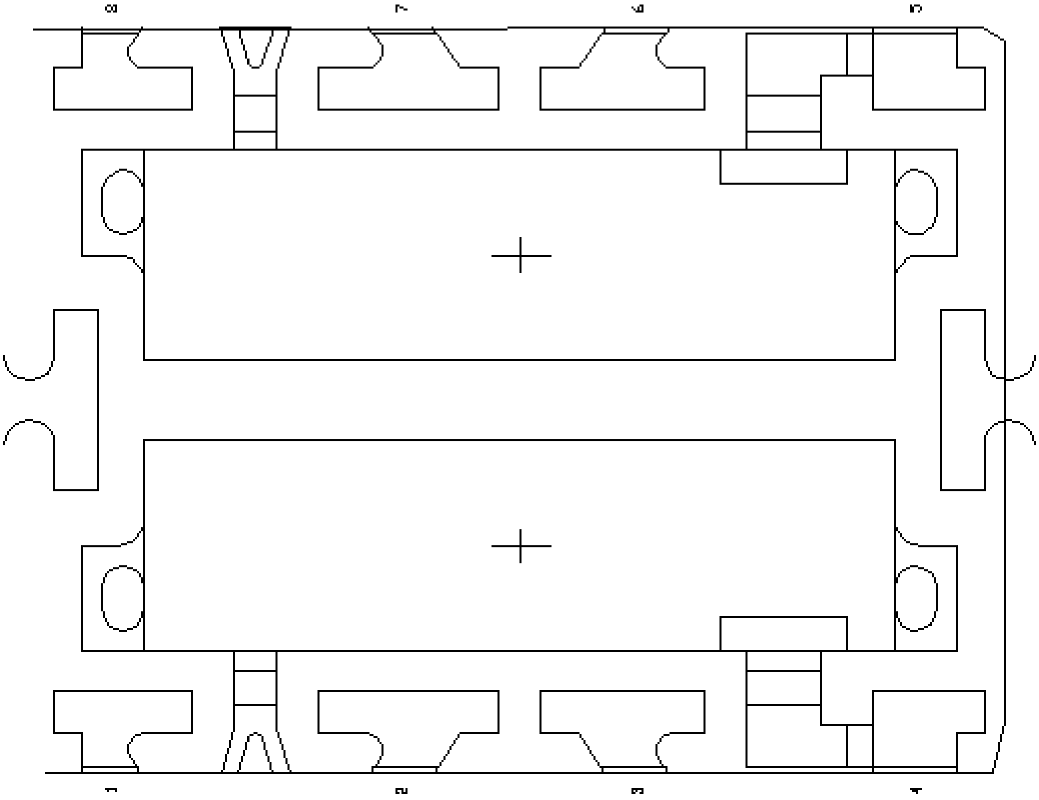
Description of Change:

Change MSA isolation devices to 1/2 etch pull out leadframe. Customers may notice the internal configuration changes particularly the lead tip geometries.

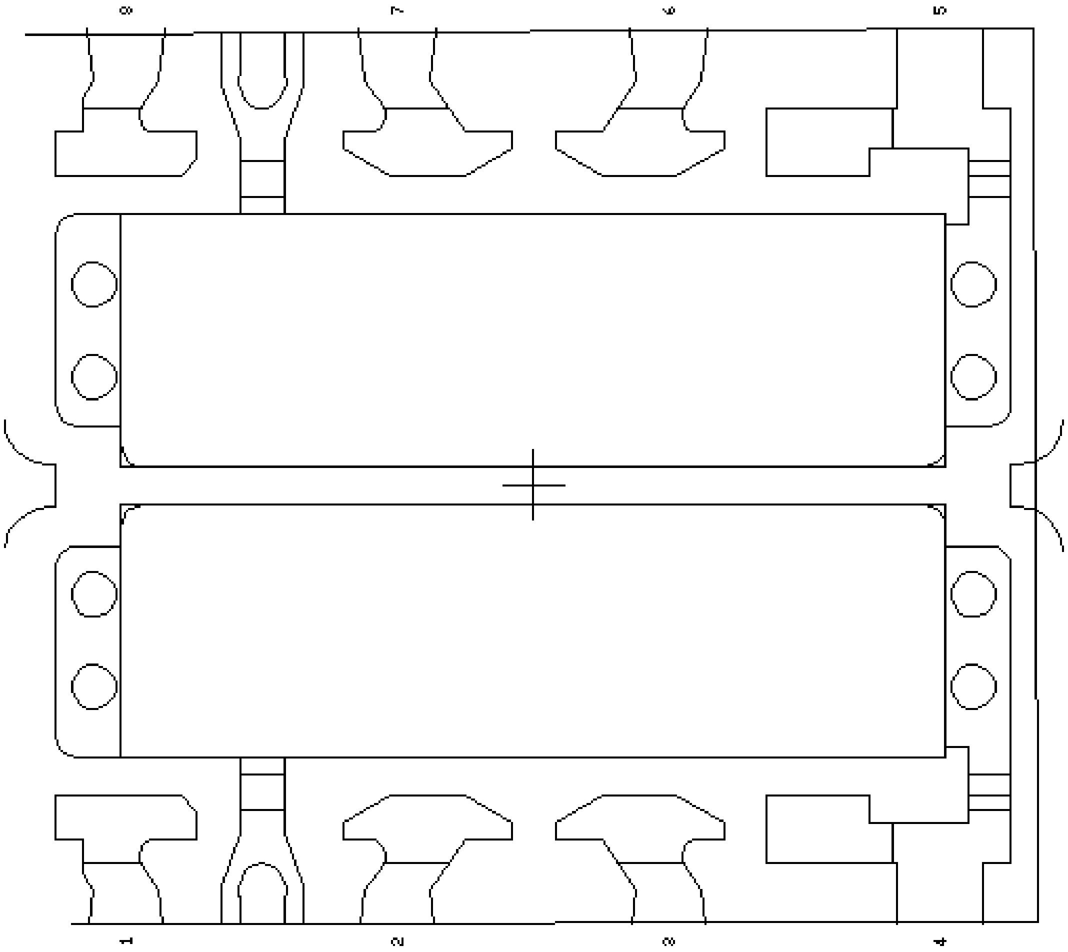
Change from configuration A:



Change from configuration B:



Change to:



Reason for Change:

Improve margin of package creep and clearance dimensions.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact.

Changes to product identification resulting from this PCN:

None

Product Affected:
Change from configuration A: ISO721QDRQ1 Change from configuration B: ISO7221CQDRQ1 ISO7221AQDRQ1 ISO7421AQDRQ1 ISO7220AQDRQ1 ISO7421QDRQ1

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com